imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



CMOS IC FROM 64K byte, RAM 4K byte on-chip 8-bit 1-chip Microcontroller with Full-Speed USB



The LC87F1D64A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 62.5ns, integrates on a single chip a number of hardware features such as 64K-byte flash ROM (onboard programmable), 4096-byte RAM, an on-chip debugger, a sophisticated 16-bit timers/counters (may be divided into 8-bit timers), 16-bit timers/counter (may be divided into 8-bit timers/counters or 8-bit PWMs), two 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a high-speed clock counter, two synchronous SIO interface (with automatic block transmit/ receive function), an asynchronous/synchronous SIO interface, a UART interface (full duplex), a Full-Speed USB interface (function controller), 12-channel 12-bit A/D converter with 12-/8-bit resolution selector, two 12-bit PWM channels, a system clock frequency divider, an infrared remote control receiver circuit, and a 30-source 10-vector address interrupt feature.

Features

■Flash ROM

- Capable of on-board-programming with wide range, 3.0 to 5.5V, of voltage source.
- Block-erasable in 128 byte units
- Writes data in 2-byte units
- 65536 × 8 bits

■RAM

• 4096 × 9 bits

■Minimum Bus Cycle

• 62.5ns (CF=16MHz)

Note: The bus cycle time here refers to the ROM read speed.

* This product is licensed from Silicon Storage Technology, Inc. (USA).



Minimum Instruction Cycle Time

• 188ns (CF=16MHz)

■Ports

• I/O ports

- no pons	
Ports whose I/O direction can be designated in 1 bit units	28 (P10 to P17, P20 to P27, P30 to P34,
	P70 to P73, PWM0, PWM1, XT2)
Ports whose I/O direction can be designated in 4 bit units	8 (P00 to P07)
• USB ports	2 (D+, D-)
 Dedicated oscillator ports 	2 (CF1, CF2)
 Input-only port (also used for oscillation) 	1 (XT1)
• Reset pins	$1(\overline{\text{RES}})$
• Power pins	6 (V _{SS} 1 to 3, V _{DD} 1 to 3)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) $\times 2$ channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

- Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 1: 16-bit timer/counter that supports PWM/toggle outputs
 - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs)
 - + 8-bit timer/counter with an 8-bit prescaler (with toggle outputs)
 - Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels
 - Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)
 - (toggle outputs also possible from the lower-order 8 bits)
 - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)
 - (The lower-order 8 bits can be used as PWM.)
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts programmable in 5 different time schemes

■SIO

- SIO0: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 512/3 tCYC
 - Automatic continuous data transmission (1 to 256 bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- SIO4: Synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - 3) Automatic continuous data transmission (1 to 4096 bytes, specifiable in 1 byte units, suspension and resumption of data transmission possible in 1 byte or 2 bytes units)
 - 4) Auto-start-on-falling-edge function
 - 5) Clock polarity selectable
 - 6) CRC16 calculator circuit built in

■Full Duplex UART

• UART1

- 1) Data length: 7/8/9 bits selectable
- 2) Stop bits: 1 bit (2 bits in continuous transmission mode)
- 3) Baud rate: 16/3 to 8192/3 tCYC
- UART2
- 1) Data length: 7/8/9 bits selectable
- 2) Stop bits: 1 bit (2 bits in continuous transmission mode)
- 3) Baud rate: 16/3 to 8192/3 tCYC
- **\blacksquare**AD Converter: 12 bits \times 12 channels
 - 12/8 bits AD converter resolution selectable

■PWM: Multifrequency 12-bit PWM × 2 channels

■Infrared Remote Control Receiver Circuit

1) Noise reduction function

(noise filter time constant: Approx. 120µs, when the 32.768kHz crystal oscillator is selected as the reference voltage source.)

- 2) Supports data encoding systems such as PPM (Pulse Position Modulation) and Manchester encoding
- 3) X'tal HOLD mode release function

■USB Interface (function controller)

- Compliant with USB 2.0 Full-Speed
- Supports a maximum of 4 user-defined endpoints.

Endpoint		EP0	EP1	EP2	EP3	EP4
Transfer	Control	0	-	-	-	-
Туре	Bulk	-	0	0	0	0
	Interrupt	-	0	0	0	0
Isochronous		-	0	0	0	0
Max. payload		64	64	64	64	64

■Watchdog Timer

• External RC watchdog timer

1) Interrupt and reset signals selectable

- Internal counter watchdog timer
 - 1) Generates an internal reset signal on overflow occurring in a timer that runs on a dedicated low-speed RC oscillator clock (30kHz).
 - 2) Three operating modes are selectable: continues counting, stops counting, or retains count when the CPU

■Clock Output Function

1) Able to output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 as system clock.

2) Able to output oscillation clock of sub clock.

■Interrupts

- 30 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/USB bus active/remote control receiver
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/USB bus reset/USB suspend/UART1 receive/UART2 receive
8	0003BH	H or L	SIO1/USB endpoint/USB-SOF/SIO4/UART1 transmit/UART2 transmit
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0/PWM0/PWM1

[•] Priority Level: X > H > L

Subroutine Stack Levels: 2048 levels (the stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits \div 16 bits (12 tCYC execution time)

■Oscillation Circuits

- RC oscillation circuit (internal): For system clock (1MHz)
- Low-speed RC oscillation circuit (internal): For watchdog timer (30kHz)
- CF oscillation circuit: For system clock
- Crystal oscillation circuit: For system clock, time-of-day clock
- PLL circuit (internal):

■Standby Function

• HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation. 1) Oscillation is not halted automatically.

For USB interface (see Fig.5)

- 2) There are three ways of resetting the HALT mode.
 - (1) Setting the reset pin to the low level
 - (2) Reset generated by watchdog timer
 - (3) Interrupt generation
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The PLL base clock generator, CF, RC and crystal oscillators automatically stop operation.
 - 2) There are five ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) Reset generated by watchdog timer
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2, INT4, and INT5 pins * The INT0 and INT1 pins must be configured only for level detection.
 - (4) Having an interrupt source established at port 0
 - (5) Having an bus active interrupt source established in the USB interface circuit

Continued on next page.

[•] Of interrupts of the same level, the one with the smallest vector address takes precedence.

Continued from preceding page.

- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer and the infrared remote control receiver circuit.
 - 1) The PLL base clock generator, CF and RC oscillator automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are seven ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Reset generated by watchdog timer
 - (3) Having an interrupt source established at one of the INT0, INT1, INT2, INT4, and INT5 pins * The INT0 and INT1 pins must be configured only for level detection.
 - (4) Having an interrupt source established at port 0
 - (5) Having an interrupt source established in the base timer circuit
 - (6) Having an bus active interrupt source established in the USB interface circuit
 - (7) Having an interrupt source established in the infrared remote control receiver circuit

■Package Form

• SQFP48(7×7): Lead-/Halogen-free type

■Development Tools

• On-chip debugger: TCB87 type B + LC87F1D64A

Flash ROM Programming Boards

Package	Programming boards
SQFP48(7×7)	W87F55256SQ

■Flash ROM Programmer

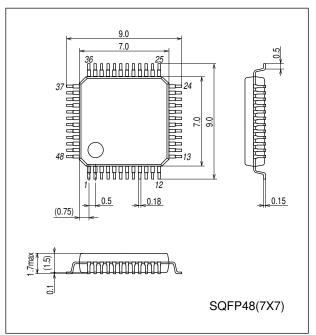
Maker		Model	Supported version	Device
Flash Support Group, Inc. (FSG)	Single Programmer	AF9708 AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev.03.06 or later	LC87F1D64A
Flash Support Group, Inc. (FSG) + Our company (Note 1)	In-circuit Programmer	AF9101/AF9103 (main body) (FSG models) SIB87 (Inter Face Driver) (Our company model)	(Note 2)	
Our company	Single/Gang Programmer In-circuit/Gang Programmer	SKK/SKK Type B (SANYO FWS) SKK-DBG Type B (SANYO FWS)	Application Version 1.04 or later Chip Data Version 2.15 or later	LC87F1D64

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together can give a PC-less, standalone on-board-programming capabilities.

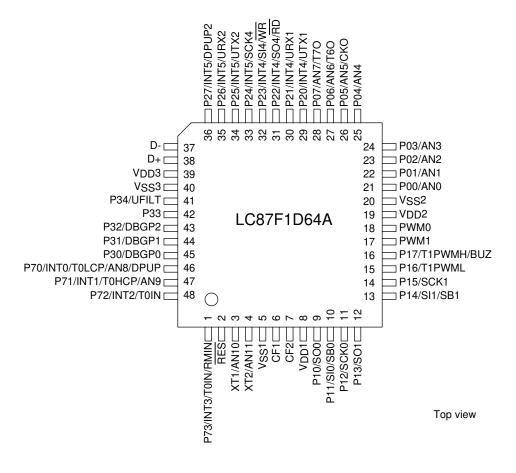
Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.

Package Dimensions

unit : mm (typ) 3163B



Pin Assignment

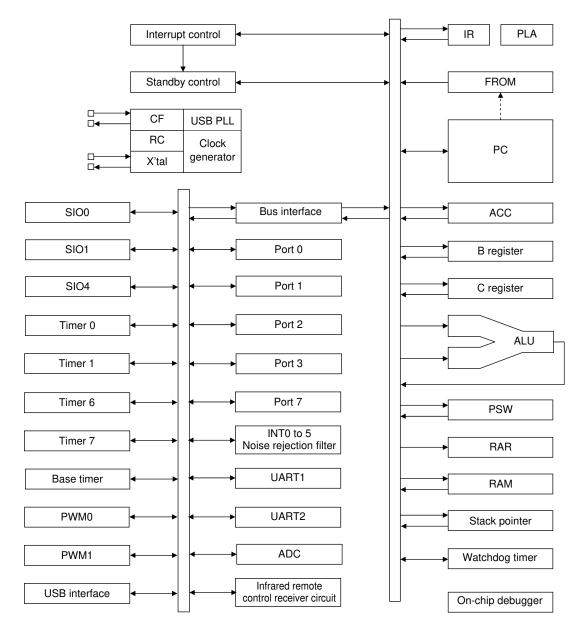


SQFP48(7×7) "Lead-/ Halogen-free Type"

SQFP48	NAME
1	P73/INT3/T0IN/RMIN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V _{SS} 1
6	CF1
7	CF2
8	V _{DD} 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1
13	P14/SI1/SB1
14	P15/SCK1
15	P16/T1PWML
16	P17/T1PWMH/BUZ
17	PWM1
18	PWM0
19	V _{DD} 2
20	V _{SS} 2
21	P00/AN0
22	P01/AN1
23	P02/AN2
24	P03/AN3

SQFP48	NAME
25	P04/AN4
26	P05/AN5/CKO
27	P06/AN6/T6O
28	P07/AN7/T7O
29	P20/INT4/UTX1
30	P21/INT4/URX1
31	P22/INT4/SO4/RD
32	P23/INT4/SI4/WR
33	P24/INT5/SCK4
34	P25/INT5/UTX2
35	P26/INT5/URX2
36	P27/INT5/DPUP2
37	D-
38	D+
39	V _{DD} 3
40	V _{SS} 3
41	P34/UFILT
42	P33
43	P32/DBGP2
44	P31/DBGP1
45	P30/DBGP0
46	P70/INT0/T0LCP/AN8/DPUP
47	P71/INT1/T0HCP/AN9
48	P72/INT2/T0IN

System Block Diagram



Pin Description

Pin Name	I/O			D	escription			Option		
V _{SS} 1, V _{SS} 2, Voc3	-	-power supply p	No							
V _{SS} 3 V _{DD} 1,	-	+power supply p	-power supply pin							
V_{DD}^2	_		valtara nin					Yes		
V _{DD} 3			USB reference voltage pin							
Port 0	I/O	8-bit I/O port						Yes		
P00 to P07		I/O specifiable		d an and aff in a	1 bit upita					
		 Pull-up resisto HOLD reset in 		d on and on in 2	+-bit units.					
		Port 0 interrup								
		Pins functions	imput							
			nnut nort: AN0	to AN7 (P00 to	P07)					
		P05: System C			10/)					
		P06: Timer 6 t	-							
		P07: Timer 7 t								
Port 1	I/O	• 8-bit I/O port	00 1					Yes		
P10 to P17		 I/O specifiable 	in 1-bit units							
		Pull-up resisto	rs can be turne	d on and off in 1	I-bit units.					
		Pin functions								
		P10: SIO0 dat	a output							
		P11: SIO0 dat	a input/bus I/O							
		P12: SIO0 clos	ck I/O							
		P13: SIO1 dat	a output							
		P14: SIO1 dat	-							
		P15: SIO1 clos								
		P16: Timer 1 F								
		P17: Timer 1 F	WMH output/b	eeper output						
Port 2	I/O	• 8-bit I/O port						Yes		
P20 to P27		I/O specifiable			()= i4 i4					
		Pull-up resisto	rs can be turne	d on and off in t	I-DIT UNITS.					
		Pin functions P20 to P22: IN		rosot input/tim	er 1 event input/	timor OL capture	input/			
			ner 0H capture	-		inner of capture	; mpu/			
				-	er 1 event input/	timer 01. capture	input/			
			ner 0H capture	-			mput			
		P20: UART1 ti								
		P21: UART1 r								
		P22: SIO4 dat	e I/O/parallel in	terface RD outp	out					
		P23: SIO4 dat	e I/O/parallel in	terface WR out	out					
		P24: SIO4 cloo								
		P25: UART2 ti	ansmit							
		P26: UART2 r	eceive							
		P27: D+ 1.5kΩ		r connect pin						
		Interrupt ackno	owledge type		1		· · · · · · · · · · · · · · · · · · ·			
			Rising	Falling	Rising & Falling	H level	L level			
		INT4	enable	enable	enable	disable	disable			
		INT5	enable	enable	enable	disable	disable			
				onabio	onabio	alcabic				

Continued on next page.

Pin Name	I/O			D	escription			Option
Port 3	I/O	• 5-bit I/O port						Yes
P30 to P34		• I/O specifiable in 1-bit units						
		Pull-up resist	ors can be turne	ed on and off in	1-bit units.			
		Pin functions						
		P34: USB inte	erface PLL filter	pin (see Fig.5)				
			gger pins: DBG	P0 to DBGP2 (P30 to P32)			
Port 7	I/O	4-bit I/O port						No
P70 to P73		-	I/O specifiable in 1-bit units					
		-	ors can be turne	ed on and off in	1-bit units.			
		Pin functions			, .		,	
		-		-	apture input/wat	tchdog timer ou	tput/	
			Ω pull-up resist	•	antura input			
		-		input/timer 0H o	ent input/timer (1	
		-	ed clock count	-			1	
				-	ent input/timer 0	H capture input/		
			P73: INT3 input (with noise filter)/timer 0 event input/timer 0H capture input/ infrared remote control receiver input					
		AD converter input port: AN8(P70), AN9(P71)						
		Interrupt acknowledge type						
			iemeage type		Rising &			
			Rising	Falling	Falling	H level	L level	
		INT0	enable	enable	disable	enable	enable	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
							11	
PWM0	I/O	• PWM0 and P	WM1 output po	rt				No
PWM1		General-purp	ose input port					
D-	I/O	• USB data I/O	pin D-					No
		General-purp	ose I/O port					
D+	I/O	• USB data I/O	pin D+					No
		General-purp	ose I/O port					
RES	Input	Reset pin						No
XT1	Input	• 32.768kHz cr	ystal oscillator i	nput pin				No
		Pin functions						
		General-purpose input port						
		AD converter input port: AN10						
		Must be conn	ected to V _{DD} 1	if not to be used	d.			
XT2	I/O	-	stal oscillator ou	utput pin				No
		Pin functions						
		General-purp	•					
			input port: AN1					
	<u> </u> .			d kept open if n	ot to be used.			
CF1	Input	Ceramic reson	ator input pin					No
CF2	Output	Ceramic reson	ator output pin					No

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
P20 to P27 P30 to P34		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
D+, D-	-	No	CMOS	No
XT1	-	No	Input only	No
XT2	-	No	32.768kHz crystal oscillator output (N channel open drain when in general- purpose output mode)	No

Note 1: Programmable pull-up resistors for port 0 are controlled in 4-bit units (P00 to 03, P04 to 07).

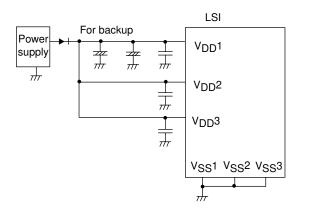
User Option Table

Option Name	Option to be Applied on	Flash-ROM Version	Option Selected in Units of	Option Selection
	D00 to D07	0	4 64	CMOS
	P00 to P07	0	1 bit	Nch-open drain
	P10 to P17	0	1 bit	CMOS
Dest extend to be	P10 10 P17	0	T DIL	Nch-open drain
Port output type	D00 to D07	0	4 64	CMOS
	P20 to P27	0	1 bit	Nch-open drain
			CMOS	
	P30 to P34 O 1 bit	Nch-open drain		
Program start		0		00000h
address	-	0	-	0FE00h
	USB Regulator	0		USE
		0	-	NONUSE
	USB Regulator	0		USE
USB Regulator	(at HOLD mode)	0	-	NONUSE
	USB Regulator	0		USE
	(at HALT mode)	0	-	NONUSE

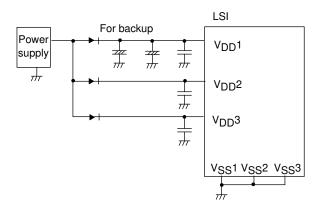
Power Pin Treatment

Connect the IC as shown below to minimize the noise input to the V_{DD1} pin. Be sure to electrically short the V_{SS1} , V_{SS2} , and V_{SS3} pins.

Example 1: When the microcontroller is in the backup state in the HOLD mode, the power to sustain the high level of output ports is supplied by their backup capacitors.



Example 2: The high level output at ports is not sustained and unstable in the HOLD backup mode.



USB Reference Power Option

When a voltage 4.5 to 5.5V is supplied to V_{DD1} and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of reference voltage circuit can be switched by the option select. The procedure for marking the option selection is described below.

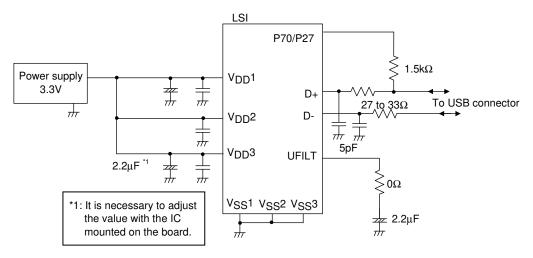
		(1)	(2)	(3)	(4)
Option select	USB Regulator	USE	USE	USE	NONUSE
	USB Regulator at HOLD mode	USE	NONUSE	NONUSE	NONUSE
	USB Regulator at HALT mode	USE	NONUSE	USE	NONUSE
Reference voltage circuit	Normal state	active	active	active	inactive
state	HOLD mode	active	inactive	inactive	inactive
	HALT mode	active	inactive	active	inactive

• When the USB reference voltage circuit is made inactive, the level of the reference voltage for USB port output is equal to V_{DD}1.

- Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.
- When the reference voltage circuit is activated, the current drain increase by approximately 100µA compared with when the reference voltage circuit is inactive.

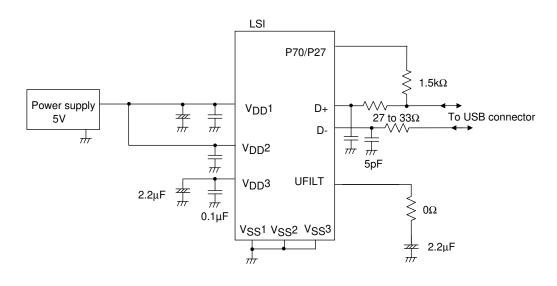
Example 1: VDD1=VDD2=3.3V

- Inactivating the reference voltage circuit (selection (4)).
- Connecting VDD3 to VDD1 and VDD2.



Example 2: VDD1=VDD2=5.0V

- Activating the reference voltage circuit (selection (1)).
- Isolating VDD3 from VDD1 and VDD2, and connecting capacitor between VDD3 and VSS.



	Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	1
	י מומווופופו	-			V _{DD} [V]	min	typ	max	unit
	ximum supply tage	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		+6.5	
np	ut voltage	V _I (1)	XT1, CF1			-0.3		V _{DD} +0.3	V
	out/output tage	V _{IO} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1, XT2			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1, 2	When CMOS output type is selected Per 1 applicable pin		-10			
		IOPH(2)	PWM0, PWM1	Per 1 applicable pin		-20			
		IOPH(3)	PH(3) Port 3 • When CMOS output P71 to P73 type is selected • Per 1 applicable pin			-5			
current	Average output current	IOMH(1)	Ports 0, 1, 2	When CMOS output type is selected Per 1 applicable pin		-7.5			
tput	(Note 1-1)	IOMH(2)	PWM0, PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-3			
Т	Total output	ΣIOAH(1)	Ports 0, 2	Total of all applicable pins		-25			
	current	ΣIOAH(2)	Port 1 PWM0, PWM1	Total of all applicable pins		-25			
		ΣIOAH(3)	Ports 0, 1, 2 PWM0, PWM1	Total of all applicable pins		-45			
		ΣIOAH(4)	Port 3 P71 to P73	Total of all applicable pins		-10			mA
		ΣIOAH(5)	D+, D-	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Ports 3, 7, XT2	Per 1 applicable pin				10	
tput current	Average output current	IOML(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				15	
outp	(Note 1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	
svel		IOML(3)	Ports 3, 7, XT2	Per 1 applicable pin				7.5	
Low level ou	Total output	$\Sigma IOAL(1)$	Ports 0, 2	Total of all applicable pins				45	
Ľ	current	ΣIOAL(2)	Port 1 PWM0, PWM1	Total of all applicable pins				45	
		ΣIOAL(3)	Ports 0, 1, 2 PWM0, PWM1	Total of all applicable pins				80	
		ΣIOAL(4)	Ports 3, 7, XT2	Total of all applicable pins				15	
		ΣIOAL(5)	D+, D-	Total of all applicable pins				25	
	owable power sipation	Pd max	SQFP48(7×7)	Ta=-30 to +70°C				190	mV
	erating ambient mperature	Topr				-30		+70	°C
	orage ambient nperature	Tstg				-55	_	+125	- (

Absolute Maximum Ratings at $Ta = 25^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 1-1: The mean output current is a mean value measured over 100ms.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Parameter	Symbol	Pin/Remarks	Conditions	r		Specific	ation	
i didilletei	Gymbol	TIMTemarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	$V_{DD}1=V_{DD}2=V_{DD}3$	0.183µs≤tCYC≤200µs		3.0		5.5	
supply voltage (Note 2-1)			0.183µs≤tCYC≤0.383µs USB circuit active		3.0		5.5	
			0.367µs≤tCYC≤200µs Except for onboard programming		2.7		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents sustained in HOLD mode.		2.0		5.5	
High level input voltage	V _{IH} (1)	Ports 0, 1, 2, 3 P71 to P73 P70 port input/ interrupt side PWM0, PWM1		2.7 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Port 70 watchdog timer side		2.7 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (3)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V _{DD}		V _{DD}	
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3 P71 to P73		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
	V _{IL} (2)	P70 port input/ interrupt side		2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 0 PWM0, PWM1		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
	V _{IL} (4)			2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (5)	Port 70 watchdog timer side		2.7 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (6)	XT1, XT2, CF1, RES		2.7 to 5.5	V _{SS}		0.25V _{DD}	
Instruction	tCYC			3.0 to 5.5	0.183		200	
cycle time			USB circuit active	3.0 to 5.5	0.183		0.383	
(Note 2-2)			Except for onboard programming	2.7 to 5.5	0.367		200	μs
External system clock frequency	FEXCF(1)	CF1	CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5%	3.0 to 5.5	0.1		16	
			 CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5% 	2.7 to 5.5	0.1		8	MH
Oscillation frequency	FmCF(1)	CF1, CF2	16MHz ceramic oscillation See Fig. 1.	3.0 to 5.5		16		
range (Note 2-3)	FmCF(2)	CF1, CF2	8MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		8		MHz
,	FmRC		Internal RC oscillation	2.7 to 5.5	0.3	1.0	2.0	1
	FmSLRC		Internal low-speed RC oscillation	2.7 to 5.5	15	30	60	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.7 to 5.5		32.768		kH2

Allowable Operating Conditions at Ta = -30° C to $+70^{\circ}$ C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

 See Fig. 2.
 2.7 to 5.5
 32.768

 Note 2-1: VDD must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Electrical Characteristics at Ta = -30° C to $+70^{\circ}$ C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	tion	
Falailletei	Symbol	FINHEINARS	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I _{IH} (2)	XT1, XT2	For input port specification VIN=VDD	2.7 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.7 to 5.5			15	
Low level input current	IIL(1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			μA
	I _{IL} (2)	XT1, XT2	For input port specification VIN=VSS	2.7 to 5.5	-1			
	I _{IL} (3)	CF1	V _{IN} =V _{SS}	2.7 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, PWM1 P05 (CK0 when	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (5)	· ·	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	using system clock output function)	I _{OH} =-1mA	2.7 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	v
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			0.4	_
	V _{OL} (3)		I _{OL} =2.5mA	2.7 to 5.5			0.4	
	V _{OL} (4)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
	V _{OL} (5)	PWM0, PWM1	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (6)	XT2	I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (7)	Ports 3, 7	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =1mA	2.7 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	kΩ
	Rpu(2)	Port 7		2.7 to 5.5	18	50	150	K52
Hysteresis voltage	VHYS	RES Ports 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		v
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

Serial I/O Characteristics at $Ta = -30^{\circ}C$ to $+70^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$ 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

	Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
	alameter	Symbol	FINITHEINAIKS	Conditions	V _{DD} [V]	min	typ	max	unit
	Frequency	tSCK(1)	SCK0(P12)	See Fig.8.		2			
	Low level pulse width	tSCKL(1)				1			
	High level pulse width	tSCKH(1)				1			
, yoc		tSCKHA(1a)		 Continuous data transmission/ reception mode USB nor SIO4 are not in use simultaneous. See Fig.8. (Note 4-1-2) 	-	4			
Input clock		tSCKHA(1b)		 Continuous data transmission/reception mode USB is in use simultaneous. SIO4 is not in use simultaneous. See Fig.8. (Note 4-1-2) 	2.7 to 5.5	7			tCYC
Serial clock		tSCKHA(1c)		 Continuous data transmission/ reception mode USB and SIO4 are in use simultaneous. See Fig.8. (Note 4-1-2) 		9			
Serial	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig.8.		4/3			
	Low level pulse width	tSCKL(2)					1/2		
	High level pulse width	tSCKH(2)					1/2		tSCK
clock		tSCKHA(2a)		 Continuous data transmission/ reception mode USB nor SIO4 are not in use simultaneous. CMOS output selected See Fig.8. 		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	
Output cl		tSCKHA(2b)		 Continuous data transmission/ reception mode USB is in use simultaneous. SIO4 is not in use simultaneous. CMOS output selected See Fig.8. 	2.7 to 5.5	tSCKH(2) +2tCYC		tSCKH(2) +(19/3) tCYC	tCYC
		tSCKHA(2c)		 Continuous data transmission/ reception mode USB and SIO4 are in use simultaneous. CMOS output selected See Fig.8. 		tSCKH(2) +2tCYC		tSCKH(2) +(25/3) tCYC	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SIORUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Continued on next page.

	_							Spec	ification	
	F	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	 Must be specified with respect to rising edge of SIOCLK. See Fig.8. 	2.7 to 5.5	0.03			
Serial input	Da	ta hold time	thDI(1)			2.7 to 5.5	0.03			
	clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-3)	2.7 to 5.5			(1/3)tCYC +0.05	μs
Serial output	Input clock		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	
Seria	Output clock		tdD0(3)		(Note 4-1-3)	2.7 to 5.5			(1/3)tCYC +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig.8.

		Dexemptor	Cumbol	Pin/Remarks	Conditions			Spec	ification	
		Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig.8.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			tCYC
clock	-	High level pulse width	tSCKH(3)				1			1010
Serial clock	쏭	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected See Fig.8.		2			
	Output clock	Low level pulse width	tSCKL(4)			2.7 to 5.5		1/2		10.014
	NO	High level pulse width	tSCKH(4)					1/2		tSCK
Serial input	Da	ta setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK.	2.7 to 5.5	0.03			
Serial	Da	ta hold time	thDI(2)		• See Fig.8.	2.7 to 5.5	0.03			
Serial output	Οι	itput delay time	tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig.8. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

 • See Fig.8.

 Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

3. SIO4 Serial I/O Characteristics (Note 4-3-1)

		Parameter	Symbol	Pin/	Conditions			Spec	ification	
	r			Remarks		V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(5)	SCK4(P24)	See Fig.8.		2			
		Low level pulse width	tSCKL(5)				1			
		High level	tSCKH(5)	-			1			
	ock	pulse width	tSCKHA(5a)		 USB nor continuous data transmission/reception mode Of SIO0 are not in use simultaneous. See Fig.8. (Note 4-3-2) 		4			
	Input clock		tSCKHA(5b)		 USB is in use simultaneous. Continuous data transmission/ reception mode of SIO0 is not in use simultaneous. See Fig.8. (Note 4-3-2) 	2.7 to 5.5	7			tCYC
Serial clock			tSCKHA(5c)		 USB and continuous data transmission/ reception mode of SIO0 are in use simultaneous. See Fig.8. (Note 4-3-2) 		10			
rial o		Frequency	tSCK(6)	SCK4(P24)	CMOS output selected		4/3			
e N	}	Low level pulse width	tSCKL(6)		• See Fig.8.			1/2		tSCK
		High level pulse width (Note 4-3-3)	tSCKH(6)					1/2		1301
	slock		tSCKHA(6a)		 USB nor continuous data transmission/reception mode of SIO0 are not in use simultaneous. CMOS output selected See Fig.8. 		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(10/3) tCYC	
	Output clock		tSCKHA(6b)		USB is in use simultaneous. Continuous data transmission/ reception mode of SIO0 is not in use simultaneous. CMOS output selected See Fig.8.	2.7 to 5.5	tSCKH(6) +(5/3) tCYC		tSCKH(6) +(19/3) tCYC	tCYC
			tSCKHA(6c)		USB and continuous data transmission/reception mode of SIO0 are in use simultaneous. CMOS output selected See Fig.8.		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(28/3) tCYC	
input	Da	ta setup time	tsDI(3)	SO4(P22), SI4(P23)	Must be specified with respect to rising edge of SIOCLK.See Fig.8.	2.7 to 5.5	0.03			
Serial input	Da	ta hold time	thDI(3)			2.7 to 5.5	0.03			μs
Serial output	Ou	tput delay time	tdD0(5)	SO4(P22), SI4(P23)	 Must be specified with respect to rising edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig.8. 	2.7 to 5.5			(1/3)tCYC +0.05	μs

Note 4-3-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-3-2: To use serial-clock-input in continuous trans/rec mode, a time from SI4RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-3-3: When using the serial clock output, make sure that the load at the SCK4 (P24) pin meets the following conditions:

Clock rise time tSCKR < 0.037 μ s (see Figure 11.) at Ta=+25°C, V_{DD}=3.3V

Deremeter	Cumhal	Din/Domostro	Conditions			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tP1H(1) tP1L(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P23),	 Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled. 	2.7 to 5.5	1			
		INT5(P24 to P27)						
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	256			
	tPIL(5)	RMIN(P73)	Recognized by the infrared remote control receiver circuit as a signal	2.7 to 5.5	4			RMCK (Note 5-1)
	tPIL(6)	RES	Resetting is enabled.	2.7 to 5.5	200			μs

Pulse Input Conditions at Ta = -30°C to +70°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 5-1: Represents the period of the reference clock (1 tCYC to 128 tCYC or the source frequency of the subclock) for the infrared remote control receiver circuit.

AD Converter Characteristics at Ta= -30° C to $+70^{\circ}$ C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

<12-bits AD Converter Mode>

Dementer	O: make al	Pin/Remarks	Quaditions		Specification				
Parameter	Symbol	FINITHEINAIKS	Conditions	V _{DD} [V]	min	typ	max	unit	
Resolution	Ν	AN0(P00) to		3.0 to 5.5		12		bit	
Absolute accuracy	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±16	LSB	
Conversion time	TCAD	AN8(P70) AN9(P71)	See conversion time calculation	4.0 to 5.5	32		115		
	,	AN9(P71) AN10(XT1)	formulas. (Note 6-2)	3.0 to 5.5	64		115	μs	
		AN11(XT2)	AD division ratio=1/16	3.0 to 5.5	50		115		
Analog input voltage range	VAIN			3.0 to 5.5	V _{SS}		V _{DD}	V	
Analog port input	IAINH]	VAIN=V _{DD}	3.0 to 5.5			1		
current	rent IAINL VAIN=VS		VAIN=V _{SS}	3.0 to 5.5	-1			μA	

<8-bits AD Converter Mode>

Damanatan	O week al	Dire (De recentor		Conditions		Specification			
Parameter	Symbol	Pin/Remarks	Conditions		V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to			3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07)	(Note 6-	-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN8(P70)	See conversion time calculation		4.0 to 5.5	20		90	
		AN9(P71) AN10(XT1)	formulas	s. (Note 6-2)	3.0 to 5.5	40		90	μs
		AN11(XT2)		AD division ratio=1/16	3.0 to 5.5	31		90	
Analog input voltage range	VAIN				3.0 to 5.5	V _{SS}		V _{DD}	v
Analog port input	IAINH	1	VAIN=V _{DD}		3.0 to 5.5			1	
current	IAINL	1	VAIN=V	SS	3.0 to 5.5	-1			μA

<Conversion time calculation formulas>

12-bits AD Converter Mode: TCAD (Conversion time) = $((52/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$ 8-bits AD Converter Mode: TCAD (Conversion time) = $((32/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$

Attecommente	Recommended Operating Conditions/											
External	Supply Voltage	System Clock	Cycle Time	AD Frequency	Conversion Tir	me (TCAD)[μs]						
oscillator FmCF[MHz]	Range V _{DD} [V]	Range Division I Di tCYC [ns]		Division Ratio (ADDIV)	12-bit AD	8-bit AD						
16	3.0 to 5.5	1/1	187.5	1/16	52.125	32.125						
10	4.0 to 5.5	1/1	250	1/8	34.8	21.5						
12	3.0 to 5.5	1/1	250	1/16	69.5	42.8						
0	4.0 to 5.5	1/1	375	1/8	52.25	32.25						
8	3.0 to 5.5	1/1	375	1/16	104.25	64.25						

<Recommended Operating Conditions>

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

• The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.

• The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Consumption Current Characteristics at Ta = -30° C to $+70^{\circ}$ C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

Parameter	Symbol	Pin/	Conditions			Specific	cation	
T diamotor	Cynisol	Remarks		V _{DD} [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		9.9	25	
(Note 7-1)	IDDOP(2)		 Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ration 	3.0 to 3.6		5.7	14	
	IDDOP(3)		FmCF=16MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 16MHz side Interval DL escillation storaged	4.5 to 5.5		12	30	
	IDDOP(4)		 Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ration 	3.0 to 3.6		6.8	17	
	IDDOP(5)		FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Integral Dily confliction mode	4.5 to 5.5		14	35	
	IDDOP(6)		 Internal PLL oscillation mode Internal RC oscillation stopped USB circuit active 1/1 frequency division ration 	3.0 to 3.6		7.7	19	
	IDDOP(7)		FmCF=16MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 16MHz side	4.5 to 5.5		16	40	mA
	IDDOP(8)		 Internal PLL oscillation mode Internal RC oscillation stopped USB circuit active 1/1 frequency division ration 	3.0 to 3.6		8.8	22	
	IDDOP(9)	1	FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		6.8	16	
	IDDOP(10)	_	FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side	3.0 to 3.6		4.1	9.7	
	IDDOP(11)	-	 Internal RC oscillation stopped 1/2 frequency division ration 	2.7 to 3.0		3.5	7.9	
	IDDOP(12)	-	FmCF=16MHz ceramic oscillation mode	4.5 to 5.5		8.2	20	
	IDDOP(13)	-	FsX'tal=32.768kHz crystal oscillation mode System clock set to 8MHz side	3.0 to 3.6		4.7	12	
	IDDOP(14)	-	Internal RC oscillation stopped	2.7 to 3.0		4.0	9.2	
	IDDOP(15)	-	• 1/2 frequency division ration • FmCF=0MHz (oscillation stopped)	4.5 to 5.5		0.73	3.5	
	IDDOP(16)	-	• FsX'tal=32.768kHz crystal oscillation mode	3.0 to 3.6		0.43	1.9	
	IDDOP(17)	-	System clock set to internal RC oscillation	2.7 to 3.0		0.37	1.5	
	IDDOP(18)	-	1/2 frequency division ration FmCF=0MHz (oscillation stopped)	4.5 to 5.5		45	174	
	IDDOP(19)	-	FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	3.0 to 3.6		18	86	μA
	IDDOP(20)	-	Internal RC oscillation stopped	2.7 to 3.0		14	63	
HALT mode consumption current (Note 7-1)	IDDHALT(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	1/2 frequency division ration HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		4.9	12	
	IDDHALT(2)		System clock set to 12MHz side Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 3.			2.6	6.3	mA
			 1/1 frequency division ration 	ļ				

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Continued on next page.

Parameter	Symbol	Symbol	Symbol	Pin/	Conditions	r		Specific	Jacon	.
i didilletei	Gymbol	Remarks		V _{DD} [V]	min	typ	max	unit		
HALT mode consumption current (Note 7-1)	IDDHALT(3)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	HALT mode FmCF=16MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 16MHz side	4.5 to 5.5		5.7	14			
	IDDHALT(4)		 Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ration 	3.0 to 3.6		3.1	7.6			
	IDDHALT(5)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		8.9	23			
	IDDHALT(6)		 Internal PLL oscillation mode Internal RC oscillation stopped USB circuit active 1/1 frequency division ration 	3.0 to 3.6		4.6	12			
	IDDHALT(7)		HALT mode FmCF=16MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 16MHz side	4.5 to 5.5		9.7	24			
	IDDHALT(8)		 Internal PLL oscillation mode Internal RC oscillation stopped USB circuit active 1/1 frequency division ration 	3.0 to 3.6		5.0	13	mA		
	IDDHALT(9)		HALT mode FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		3.0	7.2			
	IDDHALT(10)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side 	3.0 to 3.6		1.6	3.8			
	IDDHALT(11)		 Internal RC oscillation stopped 1/2 frequency division ration 	2.7 to 3.0		1.3	2.9			
	IDDHALT(12)		HALT mode FmCF=16MHz ceramic oscillation mode	4.5 to 5.5		3.5	8.6			
	IDDHALT(13)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 8MHz side	3.0 to 3.6		1.9	4.6			
	IDDHALT(14)		 Internal RC oscillation stopped 1/2 frequency division ration 	2.7 to 3.0		1.5	3.5			
	IDDHALT(15)	-	HALT mode FmCF=0MHz (oscillation stopped)	4.5 to 5.5		0.41	2.0			
	IDDHALT(16)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation 	3.0 to 3.6		0.20	0.93	-		
	IDDHALT(18)		1/2 frequency division ration HALT mode	2.7 to 3.0		0.16	0.69			
	IDDHALT(19)		FmCF=0MHz (oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode	4.5 to 5.5		32 8.8	134 60			
	IDDHALT(20)		 System clock set to 32.768kHz side Internal RC oscillation stopped 	3.0 to 3.6		6.0	40			
HOLD mode	IDDHOLD(1)	V _{DD} 1	1/2 frequency division ration HOLD mode	4.5 to 5.5		0.08	30	-		
consumption	IDDHOLD(2)	.00.	• CF1=V _{DD} or open (External clock mode)	3.0 to 3.6		0.03	18	-		
current	IDDHOLD(2)	-		2.7 to 3.0		0.03		•		
		-	HOLD mode				15	μA		
	IDDHOLD(4) IDDHOLD(5)		Internal counter watchdog timer operation	4.5 to 5.5		2.9	38	•		
	IDDHOLD(6)		mode (internal low-speed RC oscillation circuit operation)	3.0 to 3.6 2.7 to 3.0		1.4 1.2	23 20			
Timer HOLD	IDDHOLD(7)	V _{DD} 1	• CF1=V _{DD} or open (External clock mode) Timer HOLD mode	4.5 to 5.5		27	118	1		
		.00.		7.0 10 0.0		£1	110	4		
mode	IDDHOLD(8)		 CF1=V_{DD} or open (External clock mode) 	3.0 to 3.6		6.1	51			

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

USB Characteristics and Timing at Ta = 0° C to + 70° C, V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V

D				Specification			
Parameter	Symbol	Conditions	min	typ	max	unit	
High level output	V _{OH(USB)}	• $15k\Omega\pm5\%$ to GND	2.8		3.6	٧	
Low level output	V _{OL(USB)}	• 1.5kΩ±5% to 3.6 V	0.0		0.3	V	
Output signal crossover voltage	V _{CRS}		1.3		2.0	V	
Differential input sensitivity	V _{DI}	• (D+)-(D-)	0.2			V	
Differential input common mode range	V _{CM}		0.8		2.5	V	
High level input	V _{IH(USB)}		2.0			V	
Low level input	V _{IL(USB)}				0.8	٧	
USB data rise time	^t R	• R _S =27 to 33Ω, CL=50pF • V _{DD} 3=3.0 to 3.6V	4		20	ns	
USB data fall time	B data fall time t_F \bullet R _S =27 to 33 Ω \bullet V _{DD} 3=3.0 to 3		4		20	ns	

F-ROM Programming Characteristics at Ta = $+10^{\circ}$ C to $+55^{\circ}$ C, V_{SS}1 = V_{SS}2= V_{SS}3 =0V

Parameter	Symbol Pin Conditions			Specification				
	Symbol	PIN	Conditions	V _{DD} [V]	min	typ	max	unit
Onboard programming current	IDDFW(1)	V _{DD} 1	Excluding power dissipation in the microcontroller block	3.0 to 5.5		5	10	mA
Programming	tFW(1)		Erase operation			20	30	ms
time	tFW(2)		Write operation	3.0 to 5.5		40	60	μs

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Nominal	Vendor	Vendor	Vendor	Vendor	Vendor		Cir	cuit Const	ant	Operating Voltage	Oscil Stabilizat		Durali
Frequency	Name	Oscillator Name	C1	C2	Rd1	Range	typ	max	Remarks				
			[pF]] [pF]	[Ω]	[V]	[ms]	[ms]					
8MHz	MURATA	CSTCE8M00G15L**-R0	(33)	(33)	680	2.7 to 5.5	0.1	0.5	C1 and C2				
12MHz	MURATA	CSTCE12M0G15L**-R0	(33)	(33)	470	3.0 to 5.5	0.1	0.5	integrated				
16MHz	MURATA	CSTCE16M0V13L**-R0	(15)	(15)	330	3.0 to 5.5	0.05	0.25	SMD type				

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after V_{DD} goes above the operating voltage lower limit.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed
- Till the oscillation gets stabilized after the HOLD mode is reset.
- Till the oscillation gets stabilized after the X'tal HOLD mode is reset with CFSTOP (OCR register, bit 0) set to 0

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Nominal Frequency	Vendor Name				Circuit (Constant		Operating Voltage		llation tion Time	Durali
			Oscillator Name	C3	C4	Rf	Rd2	5 -	typ	max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[s]	[S]		
32.768kHz	EPSON TOYOCOM	MC-306	18	18	OPEN	560k	2.7 to 5.0	1.1	3.0	Applicable CL value=12.5pF SMD type	

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after the instruction for starting the subclock oscillation circuit is executed
- Till the oscillation gets stabilized after the HOLD mode is reset with EXTOSC (OCR register, bit 6) set to 1

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

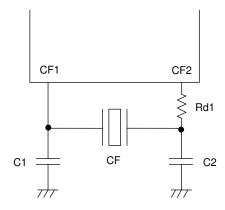


Figure 1 CF Oscillator Circuit

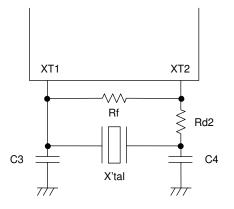


Figure 2 XT Oscillator Circuit